●USP-2B02 Power Dissipation

Power dissipation data for the USP-2B02 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 114.3mm×76.2mm

Copper (Cu) traces occupy 74.2mm x 74.2mm of the board area in back faces

Material : Glass Epoxy（FR-4）

Thickness : 1.6mm

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=150℃)

Ambient Temperature（℃）	Power Dissipation Pd（mW）	Thermal Resistance (℃/W）
25	137.5	862.07
85	71.5	
150	0